COMMENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: PMP20694</th>
<th>REV #: A</th>
<th>SUN REV #: Not In VersionControl</th>
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<tr>
<td>TID #: N/A</td>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED : 2/13/2017 8:32:14 AM</td>
<td></td>
<td>TEXAS INSTRUMENTS</td>
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